AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (currently amended) A method of producing a mask for use in producing a resist pattern for etching of a printed circuit, comprising defining in the mask a constant width etch band delineating individual conductor elements in the desired printed circuit conductor pattern.

2. (original) A method according to claim 1 wherein the etch band is of substantially the same width as the narrowest conductor or the narrowest separation between conductors in the printed circuit.

3. (original) A method according to claim 1 wherein the etch band separates the desired printed circuit conductor pattern from regions of unused conductor on the printed circuit.

4. (previously presented) A method according to claim 1 wherein the printed circuit conductor pattern includes conductor regions less than about 30 microns wide.

5. (previously presented) A method according to claim 1 wherein the printed circuit conductor pattern includes conductor regions spaced by less than about 30 microns.

6. (previously presented) A method according to claim 1 wherein the etch band is less than about 30 microns wide.

7. (previously presented) A mask for use in producing a resist pattern for etching of a printed circuit, the mask being produced by the method of claim 1.

8. (withdrawn) A printed circuit in which the printed circuit elements are delineated by a constant width etch band.

9. (withdrawn) A printed circuit according to claim 8 in which the etch band separates the printed circuit elements from regions of unused conductor.

10. (withdrawn) A printed circuit according to claim 8 wherein the etch band is of substantially the same width as the narrowest conductor or the narrowest separation between conductors in the printed circuit

11. (withdrawn) A printed circuit according to claim 8 wherein the printed circuit conductor pattern includes conductor regions less than about 30 microns wide.

12. (withdrawn) A printed circuit according to claim 8 wherein the printed circuit conductor pattern includes conductor regions spaced by less than about 30 microns.

13 (withdrawn) A printed circuit according to claim 8 wherein the etch band is less than 30 microns wide.

14. (original) A method of producing a printed circuit comprising a pattern of conductor elements, the method comprising the steps of: defining on a printed circuit substrate a pattern of resist to leave exposed regions of conductor to be etched away, the exposed regions comprising areas of constant width delineating the conductor elements.

15. (original) A method according to claim 14 wherein the conductor elements include elements less than about 30 microns wide.

16. (previously presented) A method according to claim 14 wherein the pattern includes conductor elements spaced by less than about 30 microns.

17. (previously presented) A method according to claim 14 wherein the regions of constant width are of substantially the same width as the narrowest element or narrowest separation between elements in the printed circuit.

Claims 18-19. (canceled).